SCAS103 - JANUARY 1990 - REVISED APRIL 1993

- Inputs Are TTL-Voltage Compatible
- Contains Four Flip-Flops with Double-Rail Outputs
- Clock Enable Latched to Avoid False Clocking
- Applications Include: Buffer/Storage Registers, Shift Registers, Pattern Generators
- Flow-Through Architecture to Optimize PCB Layout
- Center-Pin V<sub>CC</sub> and GND Configurations to Minimize High-Speed Switching Noise
- EPIC<sup>™</sup> (Enhanced-Performance Implanted CMOS) 1-μm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic Small Outline Packages, and Standard Plastic 300-mil DIPs

#### (TOP VIEW) 1Q 20 1Q 2Q [] 19 CLKEN 2Q [] 3 18 🛮 1D GND [ 17 2D GND [] 5 16 VCC GND [] 6 15 VCC GND II 7 14 | 3D 13 🛮 4D 3Q 🛮 8 3Q [] 9 12 CLK 11 | 4Q 4Q **1** 10

**DW OR N PACKAGE** 

### description

These circuits are positive-edge-triggered D-type flip-flops with a clock-enable input.

Information at the D inputs meeting the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock pulse if  $\overline{\text{CLKEN}}$  is low. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When the clock input is at either the high or low level, the D input signal has no effect at the output. The circuits are designed to prevent false clocking by transitions at the  $\overline{\text{CLKEN}}$  input.

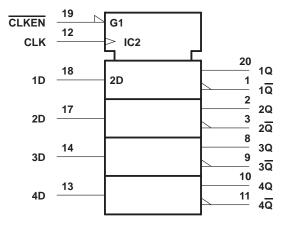
The 74ACT11379 is characterized for operation from – 40°C to 85°C.

## FUNCTION TABLE (each flip-flop)

II	NPUTS	OUTPUTS			
CLKEN	CLK	D	Q	Q	
Н	Χ	Χ	Q <sub>0</sub>	$\overline{Q}_0$	
L	$\uparrow$	Н	Н	L	
L	$\uparrow$	L	L	Н	
Х	L	Χ	Q <sub>0</sub>	$\overline{Q}_0$	

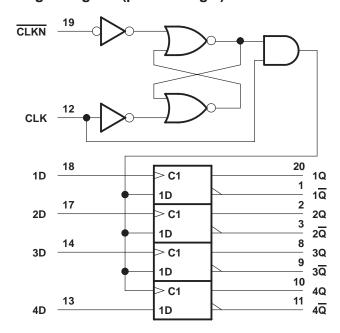
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### logic symbol†



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

### logic diagram (positive logic)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V <sub>CC</sub>	– 0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	– 0.5 V to $V_{CC}$ + 0.5 V
Output voltage range, VO (see Note 1)	– 0.5 V to V <sub>CC</sub> + 0.5 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ )	± 20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	± 50 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	$ \pm 50 \text{ mA}$
Continuous current through V <sub>CC</sub> or GND	± 200 mA
Storage temperature range	– 65°C to 150°C

<sup>&</sup>lt;sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions

		MIN	MAX	UNIT
Vcc	Supply voltage	4.5	5.5	V
VIH	High-level input voltage	2		V
VIL	Low-level input voltage		8.0	V
VI	Input voltage	0	VCC	V
VO	Output voltage	0	VCC	V
loн	High-level output current		-24	mA
l <sub>OL</sub>	Low-level output current		24	mA
Δt/Δν	Input transition rise or fall rate	0	10	ns/V
TA	Operating free-air temperature	- 40	85	°C

NOTE 1: The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEGT COMPITIONS	,,	T,	<b>Վ = 25°</b> C	;	84181		
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	UNIT
			4.4			4.4		
	ΙΟΗ = - 50 μΑ	5.5 V	5.4			5.4		
Voн	04.04	4.5 V	3.94			3.8		V
	I <sub>OH</sub> = - 24 mA		4.94			4.8		
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V				3.85		
		4.5 V			0.1		0.1	
	I <sub>OL</sub> = 50 μA	5.5 V 0	0.1		0.1	]		
VOL	I <sub>OL</sub> = 24 mA	4.5 V			0.36		0.44	V
		5.5 V			0.36		0.44	
	$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V					1.65	
lį	$V_I = V_{CC}$ or GND	5.5 V			± 0.1		± 1	μΑ
lcc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			8		80	μΑ
ΔI <sub>CC</sub> ‡	One input at 3.4 V, Other inputs at GND or V <sub>CC</sub>	5.5 V			0.9		1	mA
Ci	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V		4				pF

<sup>†</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

# timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			T <sub>A</sub> = 2	25°C				
			MIN	MAX	MIN	MAX	UNIT	
fclock	Clock frequency		0	100	0	100	MHz	
	Dulas direction	CLK high	5		5			
t <sub>W</sub>	Pulse duration	CLK low	5		5		ns	
		Data	5		5			
t <sub>su</sub>	Setup time, before CLK↑	CLKEN high	3.5		3.5		ns	
		CLKEN low	3.5		3.5			
t <sub>h</sub>	Hold time, after CLK ↑	CLKEN inactive or active, data	0	·	0		ns	

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature range (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	ТО	T,	ղ = 25°C	;	MINI	MAY		
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	UNIT	
fmax			100	125		100		MHz	
t <sub>PLH</sub>	CLIV	Any O or <del>O</del>	2.2	5	6.6	2.2	7.4		
<sup>t</sup> PHL	CLK	Any Q or Q	3.1	7.2	9.8	3.1	11.2	ns	

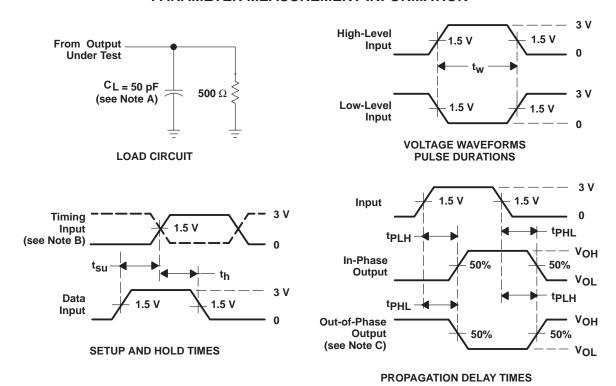
### operating characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub> Power dissipation capacitance	$C_L = 50 \text{ pF}, \qquad f = 1 \text{ MHz}$	38	pF



<sup>&</sup>lt;sup>‡</sup> This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V<sub>CC</sub>.

### PARAMETER MEASUREMENT INFORMATION



NOTES: A. CL includes probe and jig capacitance.

- B. Input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_0 = 50 \Omega$ ,  $t_f = 3 \text{ ns}$ ,  $t_f = 3 \text{ ns}$ .
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





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#### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74ACT11379DW	OBSOLETE	SOIC	DW	20	TBD	Call TI	Call TI
74ACT11379N	OBSOLETE	PDIP	N	20	TBD	Call TI	Call TI
74ACT11379N	OBSOLETE	PDIP	N	20	TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

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(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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